HIGH-VOLTAGE HIGH-CURRENT DARLINGTON TRANSISTOR ARRAYS

- **500-mA Rated Collector Current (Single Output)**
- **High-Voltage Outputs . . . 100 V**
- **Output Clamp Diodes**
- **Inputs Compatible With Various Types of Logic**
- **Relay Driver Applications**
- **Higher-Voltage Versions of ULN2003A and ULN2004A, for Commercial Temperature Range**

SN75468 . . . D, N, OR NS PACKAGE
SN75469 . . . D OR N PACKAGE
(TOP VIEW)

1B	1	16	1C
2B	2	15	2C
3B	3	14	3C
4B	4	13	4C
5B	5	12	5C
6B	6	11	6C
7B	7	10	7C
E	8	9	COM
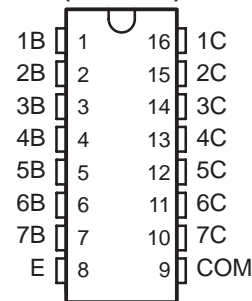
description/ordering information

The SN75468 and SN75469 are high-voltage, high-current Darlington transistor arrays. Each consists of seven npn Darlington pairs that feature high-voltage outputs with common-cathode clamp diodes for switching inductive loads. The collector-current rating of each Darlington pair is 500 mA. The Darlington pairs may be paralleled for higher current capability. Applications include relay drivers, hammer drivers, lamp drivers, display drivers (LED and gas discharge), line drivers, and logic buffers.

The SN75468 has a 2700-Ω series base resistor for each Darlington pair for operation directly with TTL or 5-V CMOS. The SN75469 has a 10.5-kΩ series base resistor to allow its operation directly with CMOS or PMOS that use supply voltages of 6 to 15 V. The required input current is below that of the SN75468.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP (N)	Tube of 25	SN75468N	SN75468N
	SOIC (D)	Tube of 40	SN75468D	SN75468
		Reel of 2500	SN75468DR	
	SOP (NS)	Reel of 2000	SN75468NSR	SN75468
	PDIP (N)	Tube of 25	SN75469N	SN75469N
	SOIC (D)	Tube of 40	SN75469D	SN75469
		Reel of 2500	SN75469DR	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Copyright © 2004, Texas Instruments Incorporated
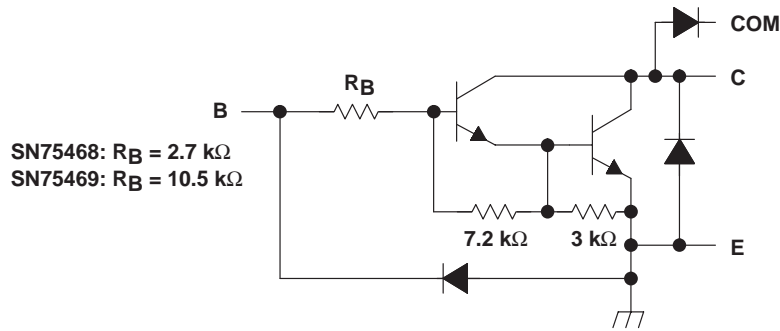
TEXAS INSTRUMENTS

SN75468, SN75469
DARLINGTON TRANSISTOR ARRAYS

SLRS023D – DECEMBER 1976 – REVISED NOVEMBER 2004

logic diagram
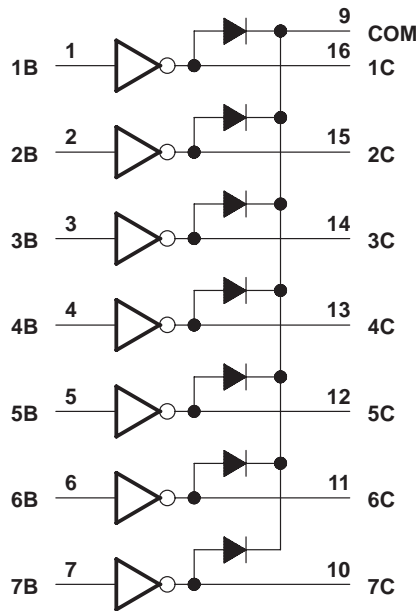
schematic (each Darlington pair)

SN75468: R_B = 2.7 kΩ
SN75469: R_B = 10.5 kΩ

7.2 kΩ 3 kΩ

All resistor values shown are nominal.

absolute maximum ratings at 25°C free-air temperature (unless otherwise noted)†

Collector-emitter voltage, V_{CE} .... 100 V
Input voltage, V_I (see Note 1) .... 30 V
Peak collector current (see Figures 14 and 15) .... 500 mA
Output clamp current, I_{OK} .... 500 mA
Total emitter-terminal current .... −2.5 A
Package thermal impedance, θ_{JA} (see Notes 2 and 3): D package .... 73°C/W
N package .... 67°C/W
NS package .... 64°C/W
Operating virtual junction temperature, T_J .... 150°C
Storage temperature range, T_{stg} .... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to the emitter/substrate terminal E, unless otherwise noted.
2. Maximum power dissipation is a function of T_J(max), θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) – T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
3. The package thermal impedance is calculated in accordance with JESD 51-7.

electrical characteristics, T_A = 25°C (unless otherwise noted)

PARAMETER		TEST FIGURE	TEST CONDITIONS		SN75468			SN75469			UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	
$V_{I(on)}$	On-state input voltage	5	V_{CE} = 2 V	I_C = 125 mA						5	V
				I_C = 200 mA			2.4			6	
				I_C = 250 mA			2.7				
				I_C = 275 mA						7	
				I_C = 300 mA			3				
				I_C = 350 mA						8	
$V_{CE(sat)}$	Collector-emitter saturation voltage	6	I_I = 250 µA,	I_C = 100 mA		0.9	1.1		0.9	1.1	V
			I_I = 350 µA,	I_C = 200 mA		1	1.3		1	1.3	
			I_I = 500 µA,	I_C = 350 mA		1.2	1.6		1.2	1.6	
V_F	Clamp-diode forward voltage	8	I_F = 350 mA			1.7	2		1.7	2	V
I_{CEX}	Collector cutoff current	1	V_{CE} = 100 V,	I_I = 0			50			50	µA
			V_{CE} = 100 V,	I_I = 0			100			100	
		2	T_A = 70°C	V_I = 1 V						500	
$I_{I(off)}$	Off-state input current	3	V_{CE} = 50 V, T_A = 70°C	I_C = 500 µA,	50	65		50	65		µA
I_I	Input current	4	V_I = 3.85 V			0.93	1.35				mA
			V_I = 5 V						0.35	0.5	
			V_I = 12 V						1	1.45	
I_R	Clamp-diode reverse current	7	V_R = 100 V				50			50	µA
			V_R = 100 V,	T_A = 70°C			100			100	
C_i	Input capacitance		V_I = 0,	f = 1 MHz		15	25		15	25	pF

switching characteristics, T_A = 25°C free-air temperature

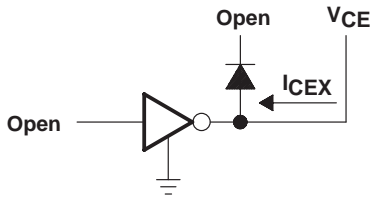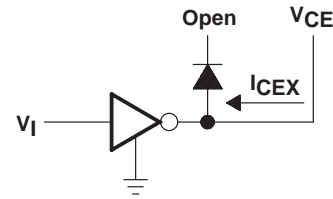| PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay time, low-to-high-level output	V_S = 50 V, R_L = 163 Ω, C_L = 15 pF, See Figure 9		0.25	1	µs
t_{PHL}	Propagation delay time, high-to-low-level output			0.25	1	µs
V_{OH}	High-level output voltage after switching	V_S = 50 V, I_O ≈ 300 mA, See Figure 10	V_S − 20			mV

PARAMETER MEASUREMENT INFORMATION
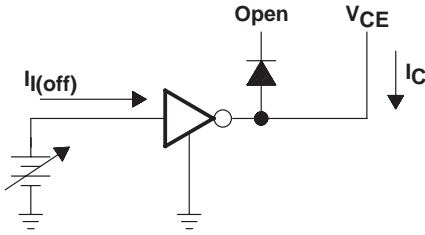
Figure 1. I_{CEX}
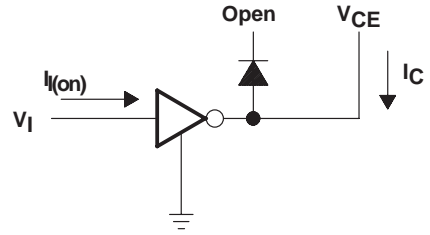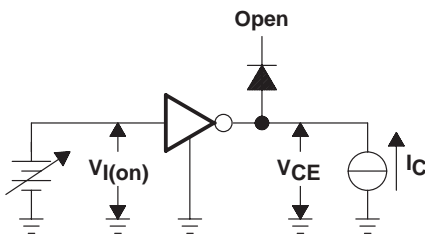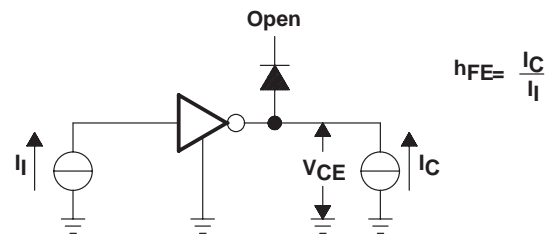
Figure 2. I_{CEX}

Figure 3. $I_{I(off)}$

Figure 4. I_I

Figure 5. $V_{I(on)}$

NOTE: I_I is fixed for measuring $V_{CE(sat)}$, variable for measuring h_{FE}.
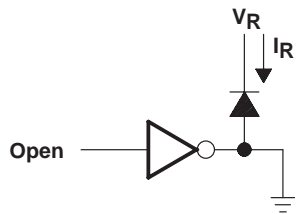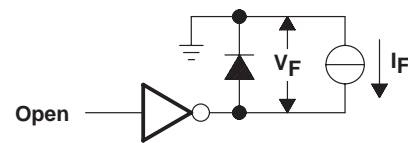
Figure 6. h_{FE}, $V_{CE(sat)}$

$$h_{FE} = \frac{I_C}{I_I}$$

Figure 7. I_R

Figure 8. V_F

PARAMETER MEASUREMENT INFORMATION
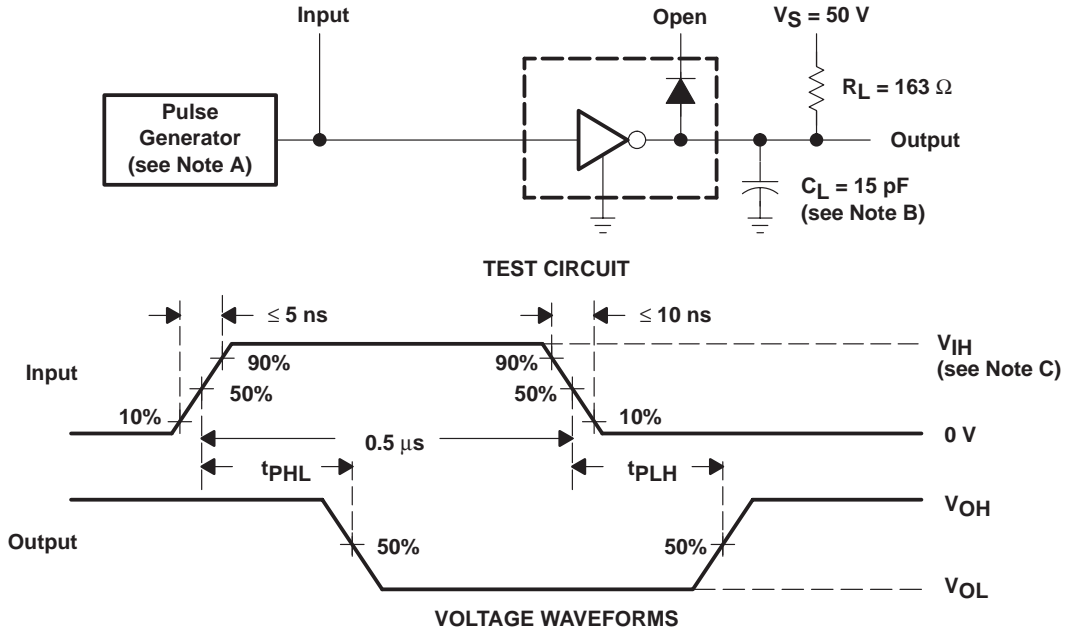
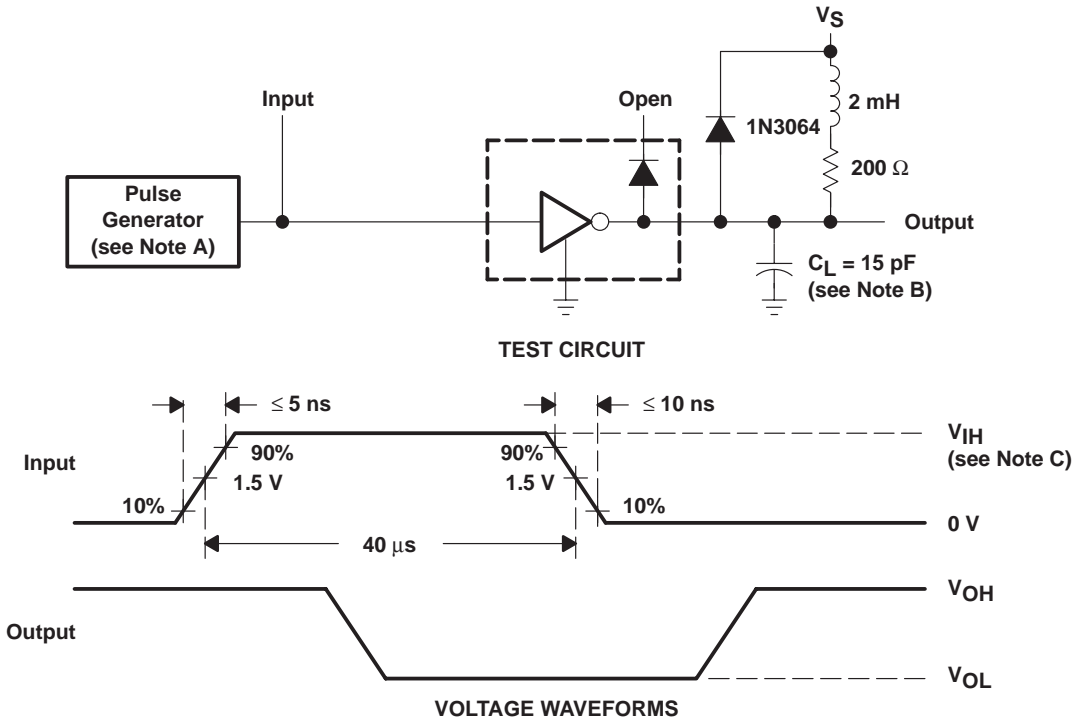**Figure 9. Test Circuit and Voltage Waveforms**

Figure 10. Latch-Up Test Circuit and Voltage Waveforms

NOTES: A. The pulse generator has the following characteristics: PRR = 12.5 kHz, Z_O = 50 Ω.
   B. C_L includes probe and jig capacitance.
   C. For testing the '468, V_{IH} = 3 V; for the '469, V_{IH} = 8 V.

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TYPICAL CHARACTERISTICS

**COLLECTOR-EMITTER
SATURATION VOLTAGE
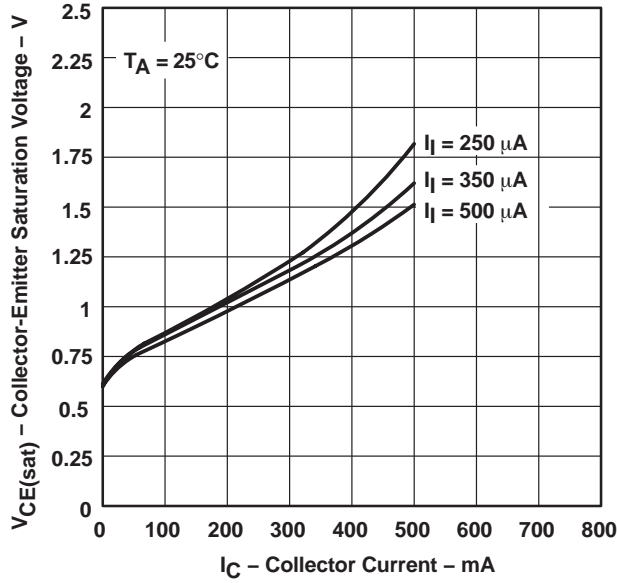vs
COLLECTOR CURRENT
(ONE DARLINGTON)**

Figure 11

**COLLECTOR-EMITTER
SATURATION VOLTAGE
vs
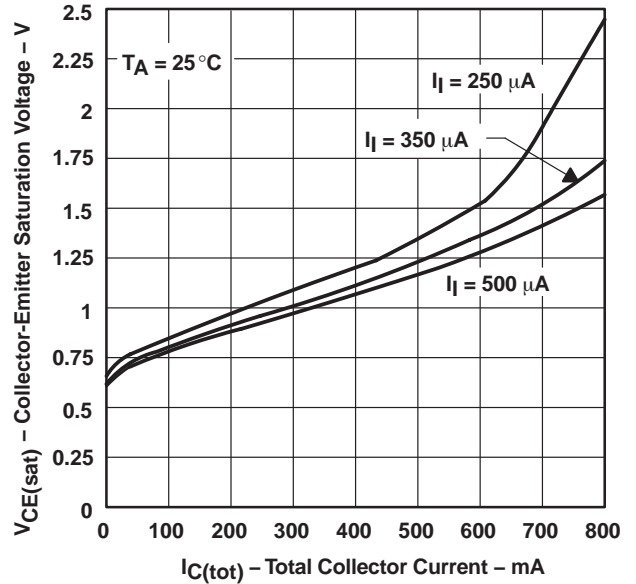COLLECTOR CURRENT
(TWO DARLINGTONS PARALLELED)**

Figure 12

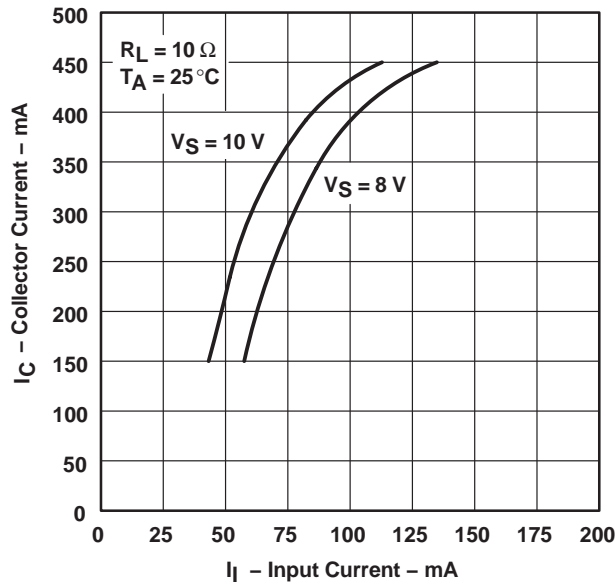**COLLECTOR CURRENT
vs
INPUT CURRENT**

Figure 13

TEXAS
INSTRUMENTS

POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

7

THERMAL INFORMATION

D PACKAGE
MAXIMUM COLLECTOR CURRENT
vs
DUTY CYCLE
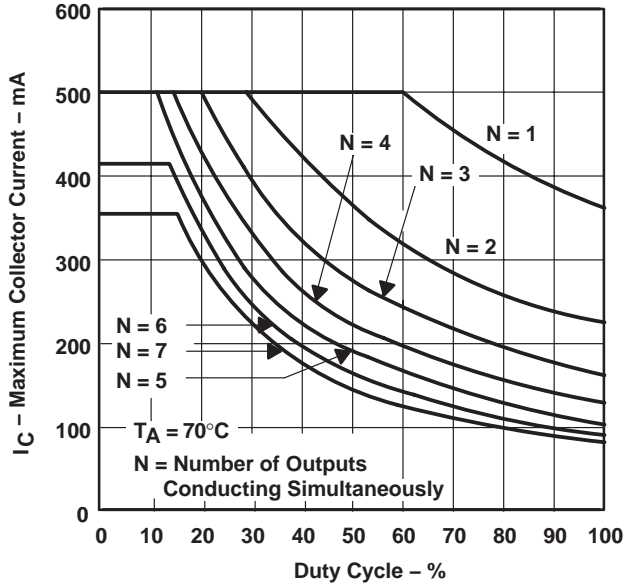
Figure 14

N PACKAGE
MAXIMUM COLLECTOR CURRENT
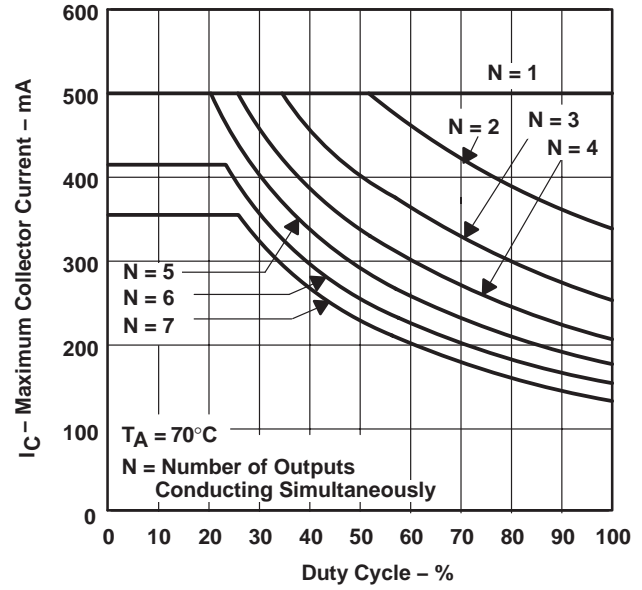**vs**
DUTY CYCLE

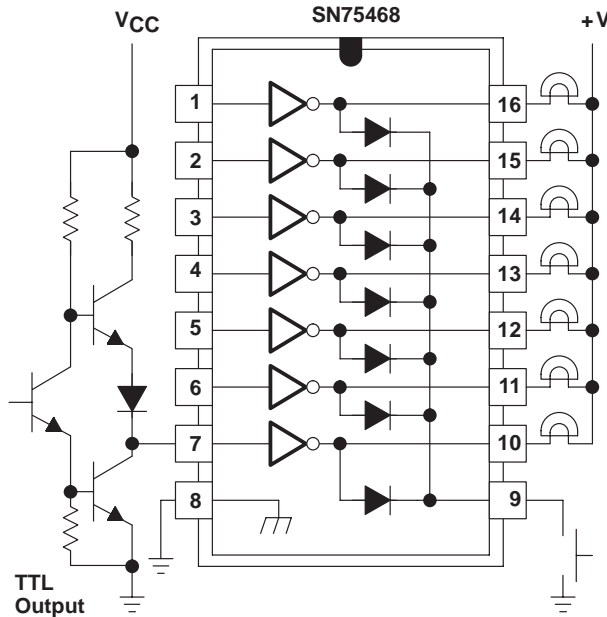**Figure 15**

APPLICATION INFORMATION
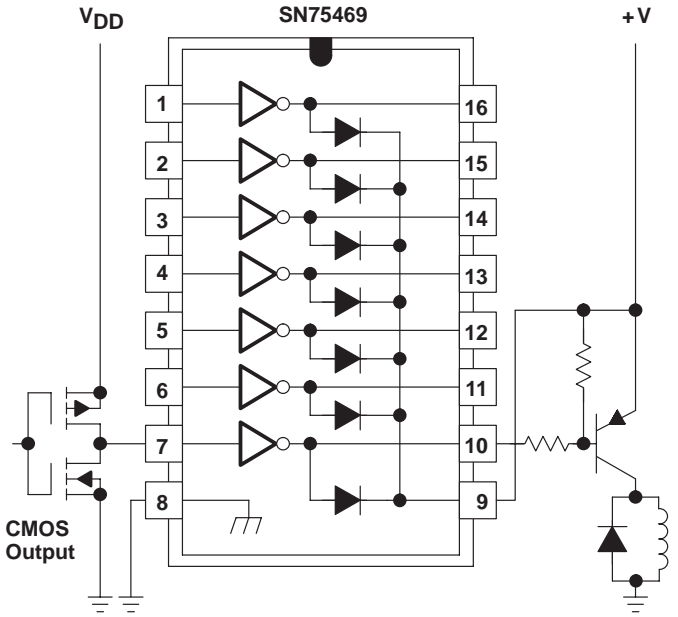

Figure 16. TTL to Load

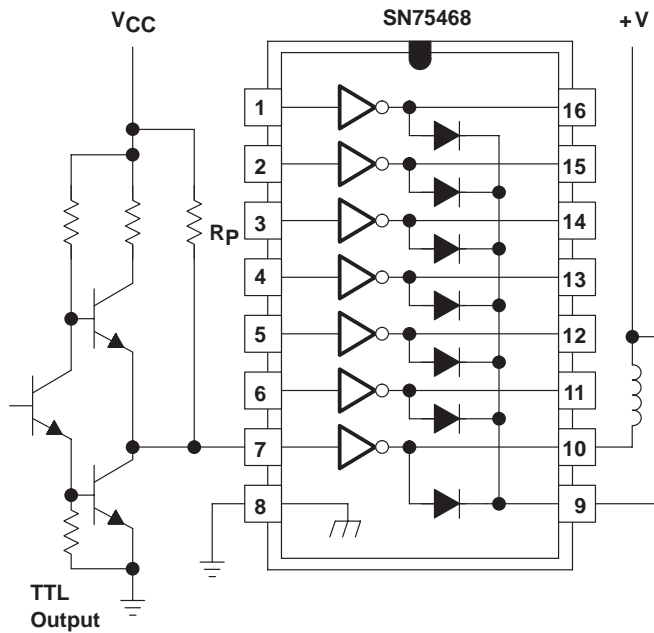**Figure 17. Buffer for Higher Current Loads**

Figure 18. Use of Pullup Resistors to Increase Drive Current

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN75468D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75468	Samples
SN75468DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75468	Samples
SN75468DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75468	Samples
SN75468DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75468	Samples
SN75468N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN75468N	Samples
SN75468NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN75468N	Samples
SN75468NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75468	Samples
SN75468NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75468	Samples
SN75469D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75469	Samples
SN75469DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75469	Samples
SN75469DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75469	Samples
SN75469DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75469	Samples
SN75469N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN75469N	Samples
SN75469NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN75469N	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75469DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

![Texas Instruments logo] **PACKAGE MATERIALS INFORMATION**

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75469DR	SOIC	D	16	2500	333.2	345.9	28.6

N (R–PDIP–T**)   PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN

DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
△C MS–001 VARIATION	AA	BB	AC	AD

0.260 (6,60) / 0.240 (6,10)

0.070 (1,78) / 0.045 (1,14) △D

0.045 (1,14) / 0.030 (0,76) △D

0.020 (0,51) MIN

0.200 (5,08) MAX

Seating Plane

0.125 (3,18) MIN

0.100 (2,54)

0.021 (0,53) / 0.015 (0,38)

⊕ 0.010 (0,25) Ⓜ

14/18 Pin Only
20 Pin vendor option △D

0.325 (8,26) / 0.300 (7,62)

0.015 (0,38)

Gauge Plane

0.010 (0,25) NOM

0.430 (10,92) MAX

4040049/E   12/2002

NOTES: A. All linear dimensions are in inches (millimeters).
          B. This drawing is subject to change without notice.
     △C   Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
     △D   The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R−PDSO−G16)   PLASTIC SMALL OUTLINE

0.394 (10,00)
0.386 (9,80)
△C

16   9

0.244 (6,20)
0.228 (5,80)

0.157 (4,00)
0.150 (3,80) △D

1   8

Pin 1
Index Area

0.050 (1,27)

0.020 (0,51)
0.012 (0,31)

⊕ 0.010 (0,25) Ⓜ

0.069 (1,75) Max

0.010 (0,25)
0.004 (0,10)

0.010 (0,25)
0.005 (0,13)

0.004 (0,10)

Gauge Plane

Seating Plane

0.010 (0,25)   0°−8°

0.050 (1,27)
0.016 (0,40)

4040047−6/M   06/11

NOTES: A.   All linear dimensions are in inches (millimeters).
          B.   This drawing is subject to change without notice.
        △C   Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall
               not exceed 0.006 (0,15) each side.
        △D   Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
          E.   Reference JEDEC MS−012 variation AC.

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D (R−PDSO−G16)   PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)

Stencil Openings
(Note D)

14x1,27

16x0,55

14x1,27

16x1,50

5,40

5.40

Example
Non Soldermask Defined Pad

Example
Pad Geometry
(See Note C)

0,60

1,55

Example
Solder Mask Opening
(See Note E)

0,07

All Around

4211283−4/E 08/12

NOTES: A.   All linear dimensions are in millimeters.
          B.   This drawing is subject to change without notice.
          C.   Publication IPC−7351 is recommended for alternate designs.
          D.   Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
               contact their board assembly site for stencil design recommendations. Refer to IPC−7525 for other stencil recommendations.
          E.   Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN

DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.
   B. This drawing is subject to change without notice.
   C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

IMPORTANT NOTICE

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Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
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DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
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RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		